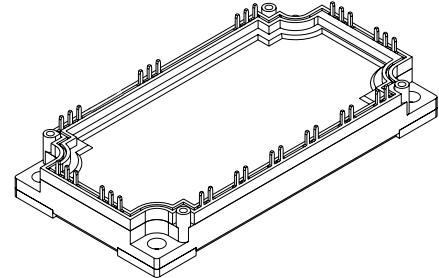
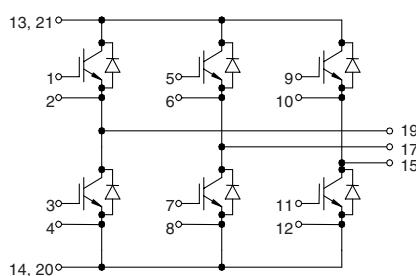


IGBT Modules

Sixpack

Short Circuit SOA Capability
Square RBSOA

I_{C25} = 160 A
 V_{CES} = 1200 V
 $V_{CE(sat)\ typ.}$ = 2.2 V



IGBTs

Symbol	Conditions	Maximum Ratings		
V_{CES}	$T_{VJ} = 25^\circ\text{C}$ to 150°C	1200		V
V_{GES}		± 20		V
I_{C25}	$T_C = 25^\circ\text{C}$	160		A
I_{C80}	$T_C = 80^\circ\text{C}$	110		A
RBSOA	$V_{GE} = \pm 15 \text{ V}$; $R_G = 6.8 \Omega$; $T_{VJ} = 125^\circ\text{C}$ Clamped inductive load; $L = 100 \mu\text{H}$	$I_{CM} = 200$ $V_{CEK} \leq V_{CES}$		A
t_{sc} (SCSOA)	$V_{CE} = V_{CES}$; $V_{GE} = \pm 15 \text{ V}$; $R_G = 6.8 \Omega$; $T_{VJ} = 125^\circ\text{C}$ non-repetitive	10		μs
P_{tot}	$T_C = 25^\circ\text{C}$	640		W

Symbol	Conditions	Characteristic Values		
		($T_{VJ} = 25^\circ\text{C}$, unless otherwise specified)		
$V_{CE(sat)}$	$I_C = 100 \text{ A}$; $V_{GE} = 15 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	2.2 2.5	2.6 V	V
$V_{GE(th)}$	$I_C = 4 \text{ mA}$; $V_{GE} = V_{CE}$	4.5	6.5	V
I_{CES}	$V_{CE} = V_{CES}$; $V_{GE} = 0 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	4	6.3	mA mA
I_{GES}	$V_{CE} = 0 \text{ V}$; $V_{GE} = \pm 20 \text{ V}$		400	nA
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on} E_{off}	$\left. \begin{array}{l} \text{Inductive load, } T_{VJ} = 125^\circ\text{C} \\ V_{CE} = 600 \text{ V}; I_C = 100 \text{ A} \\ V_{GE} = \pm 15 \text{ V}; R_G = 6.8 \Omega \end{array} \right\}$	100 60 600 90 16.1 14.6	ns ns ns ns mJ mJ	
C_{ies}		6.5		nF
Q_{Gon}		475		nC
R_{thJC}			0.19	K/W

IXYS reserves the right to change limits, test conditions and dimensions.

Diodes

Symbol	Conditions	Maximum Ratings		
I _{F25}	T _C = 25°C	200	A	
I _{F80}	T _C = 80°C	130	A	

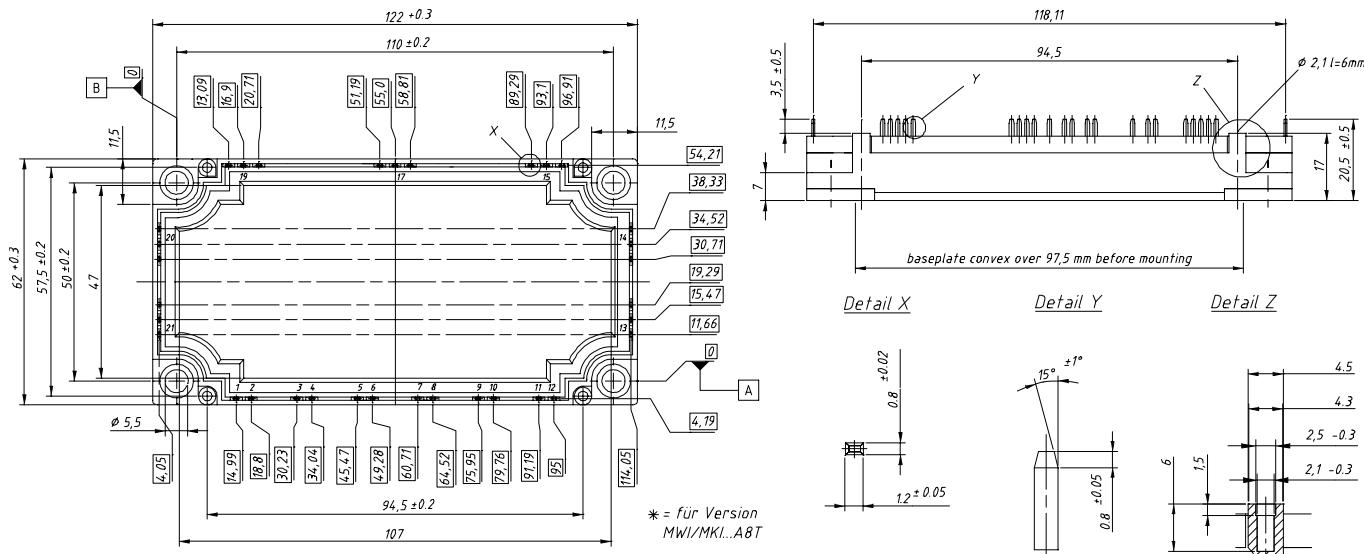
Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
V _F	I _F = 100 A; V _{GE} = 0 V; T _{VJ} = 25°C T _{VJ} = 125°C	2.3	2.6	V
		1.7		V
I _{RM} t _{rr}	I _F = 120 A; di _F /dt = -750 A/μs; T _{VJ} = 125°C V _R = 600 V; V _{GE} = 0 V	82		A
		200		ns
R _{thJC}	(per diode)		0.3	K/W

Module

Symbol	Conditions	Maximum Ratings		
T _{VJ}	operating	-40...+125	°C	
T _{JM}		+150	°C	
T _{stg}		-40...+125	°C	
V _{ISOL}	I _{ISOL} ≤ 1 mA; 50/60 Hz	2500	V~	
M _d	Mounting torque (M5)	3 - 6	Nm	

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
R _{pin-chip}			1.8	mΩ
d _s	Creepage distance on surface	10		mm
d _A	Strike distance in air	10		mm
R _{thCH}	with heatsink compound	0.01		K/W
Weight		300		g

Dimensions in mm (1 mm = 0.0394")

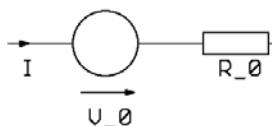


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Equivalent Circuits for Simulation

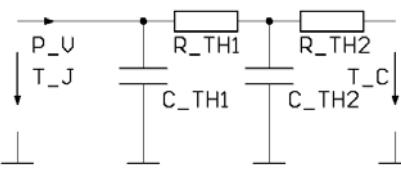
Conduction



IGBT (typ. at V_{GE} = 15 V; T_J = 125°C)
V_θ = 1.3 V; R_θ = 12 mΩ

Free Wheeling Diode (typ. at T_J = 125°C)
V_θ = 1.27 V; R_θ = 4.3 mΩ

Thermal Response



IGBT (typ.)
C_{th1} = 0.397 J/K; R_{th1} = 0.141 K/W
C_{th2} = 2.243 J/K; R_{th2} = 0.049 K/W

Free Wheeling Diode (typ.)
C_{th1} = 0.301 J/K; R_{th1} = 0.238 K/W
C_{th2} = 2.005 J/K; R_{th2} = 0.062 K/W

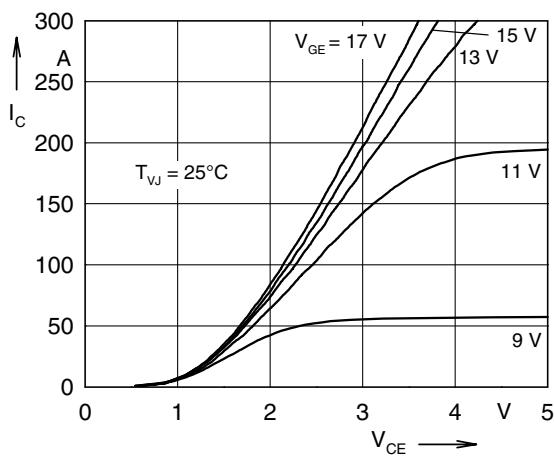


Fig. 1 Typ. output characteristics

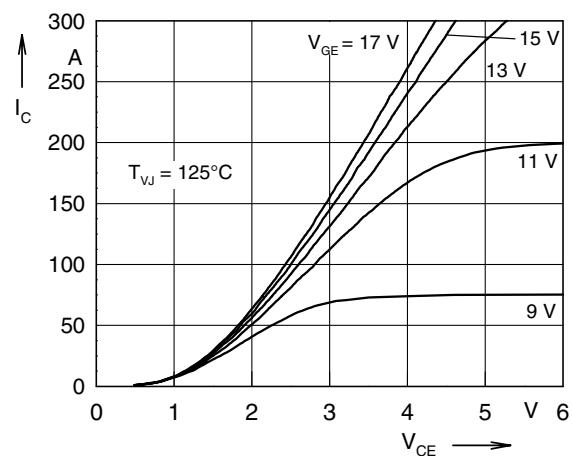


Fig. 2 Typ. output characteristics

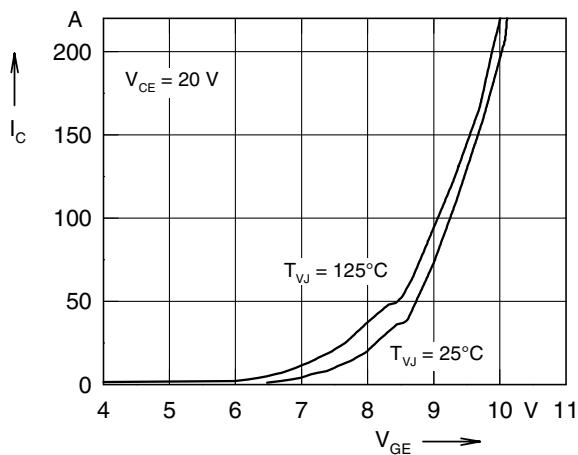


Fig. 3 Typ. transfer characteristics

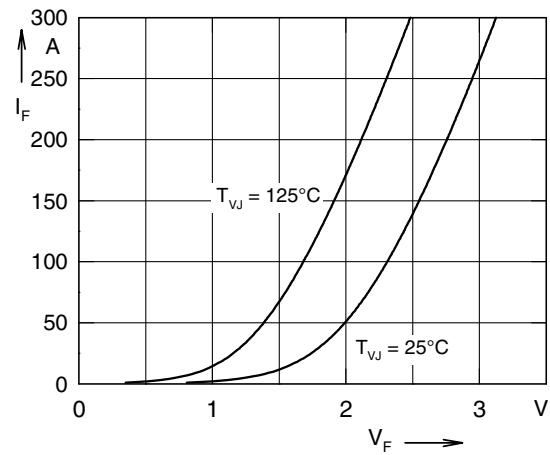


Fig. 4 Typ. forward characteristics of free wheeling diode

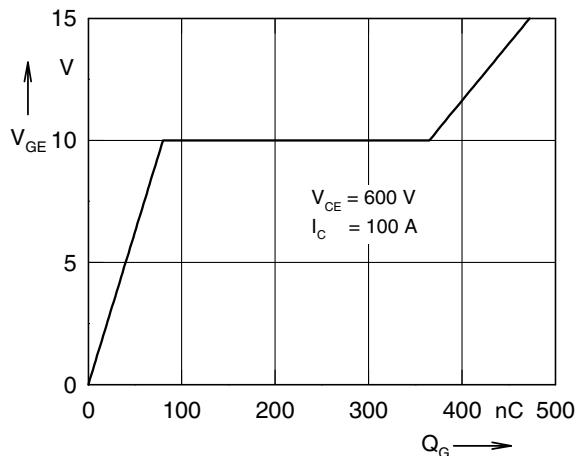


Fig. 5 Typ. turn on gate charge

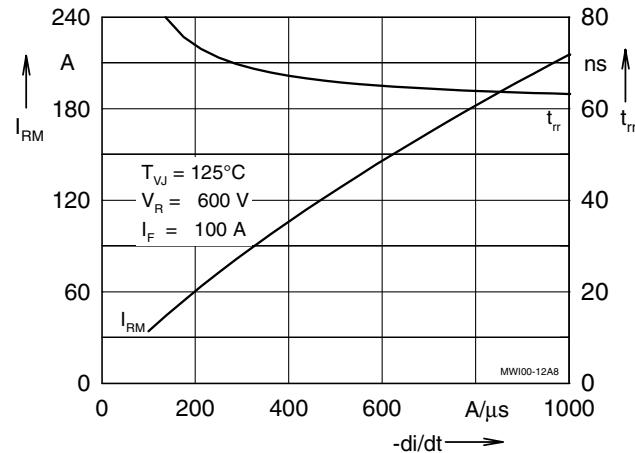


Fig. 6 Typ. turn off characteristics of free wheeling diode

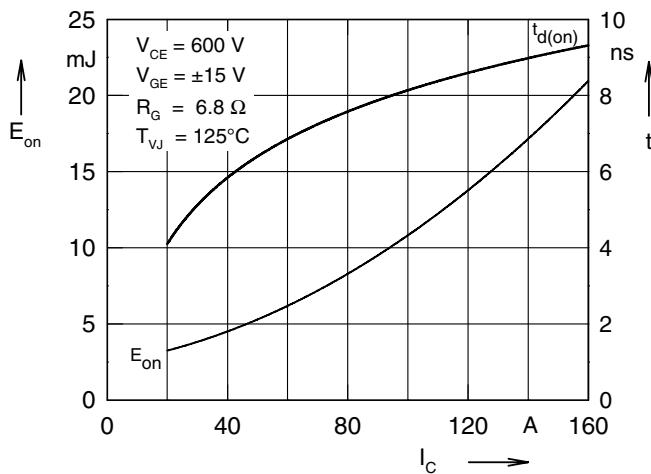


Fig. 7 Typ. turn on energy and switching times versus collector current

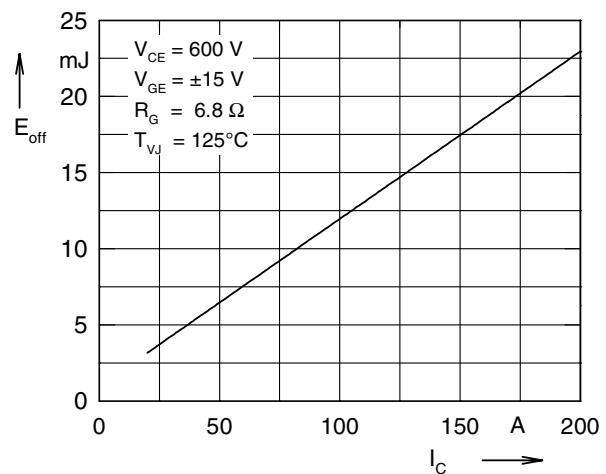


Fig. 8 Typ. turn off energy and switching times versus collector current

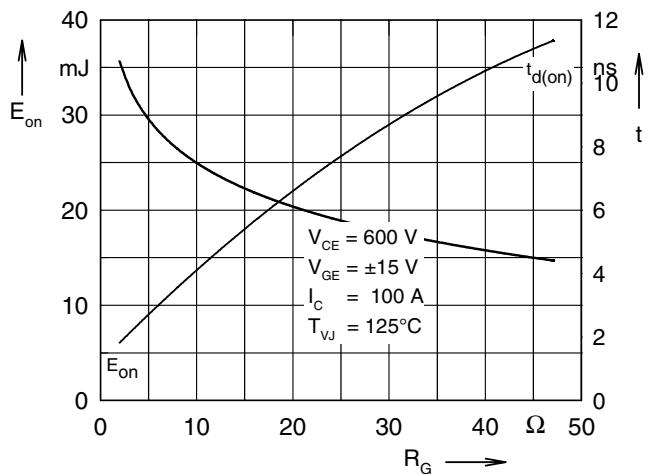


Fig. 9 Typ. turn on energy and switching times versus gate resistor

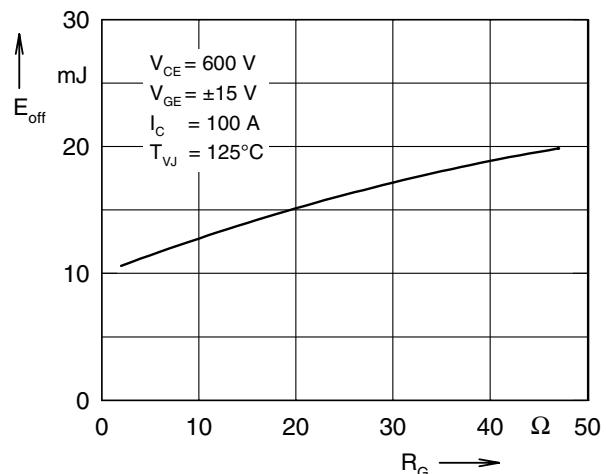


Fig. 10 Typ. turn off energy and switching times versus gate resistor

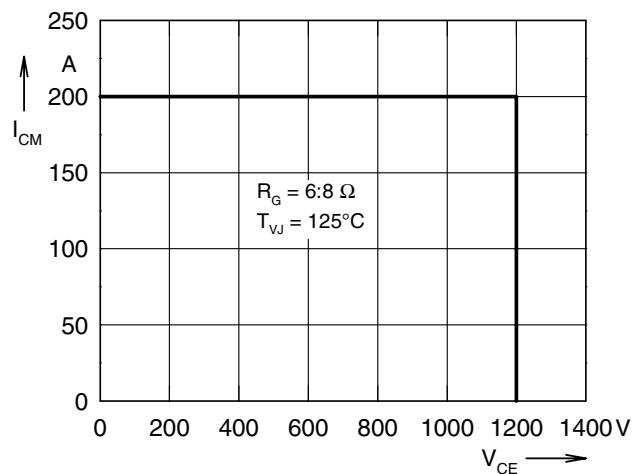


Fig. 11 Reverse biased safe operating area RBSOA

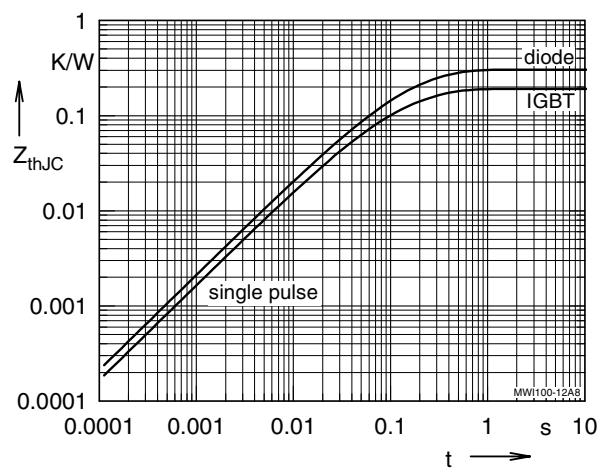


Fig. 12 Typ. transient thermal impedance